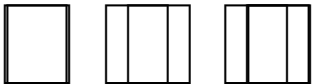




/ Revised record

	! " #	\$! % & ,	! () % * +	-	. /
	□ □	0 &	的测试条件原先为: 改成:	1 2 3	4 5 6
	□ □		7 8 9 ; < = > ? @ A < = B C	D E	4 5 6
	□ □		英文描述 更正为	D E	



/ Features

/ Applications

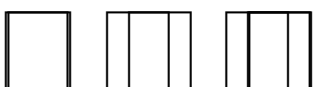
/ Equivalent Circuit



The figure consists of two panels illustrating a two-dimensional lattice. The left panel shows a grid of sites with several clusters of sites highlighted by rectangles. Some sites are labeled 'j' and 'k'. The right panel shows a similar lattice with labels 'l', 'm', 'k', 'n', 'o', 'h' and a temperature symbol 'T' at the bottom right.

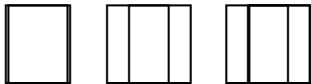
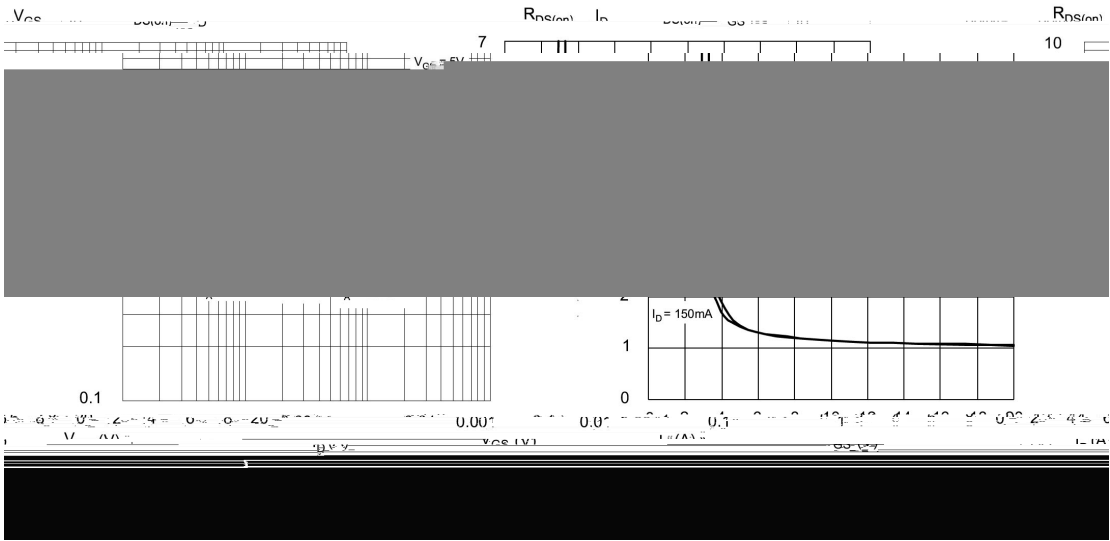
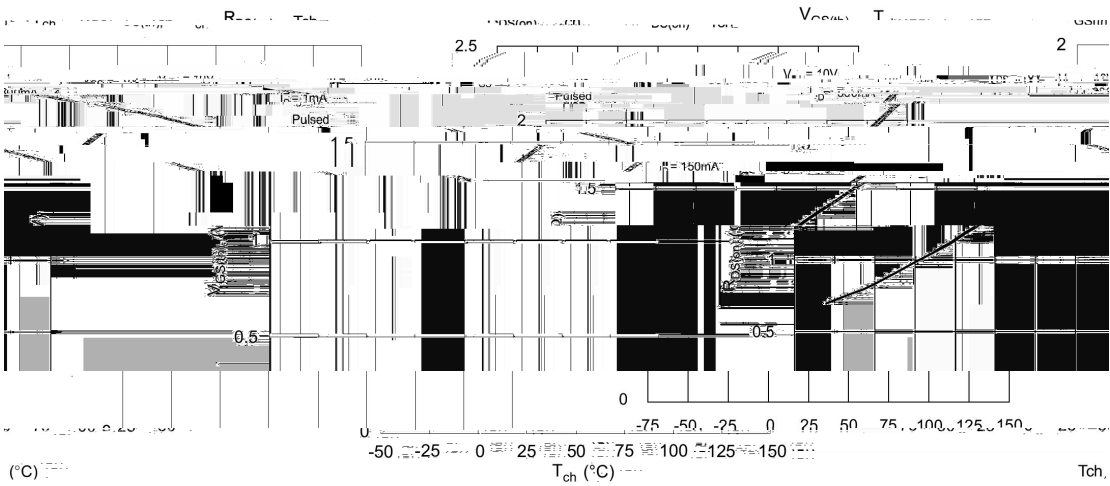
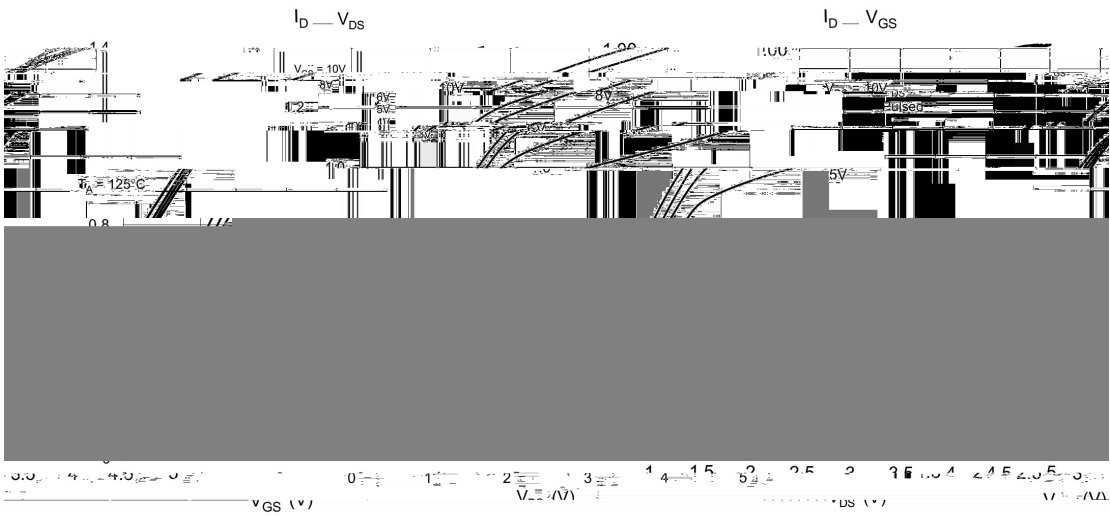
/ Electrical Characteristics(Ta=25)

A complex grid of overlapping rectangles, similar to the one above, but with a different arrangement of overlaps. The labels at the top are: j, k, l, m, p, q, r, s, t, u, v, w, x, n, o, h. The grid is composed of many overlapping rectangles of various sizes, creating a dense, layered appearance. The labels are positioned above the grid, with some labels like 'j' and 'k' appearing above a single rectangle, while others like 'p' and 'q' appear above multiple overlapping rectangles.





/ Electrical Characteristic Curve

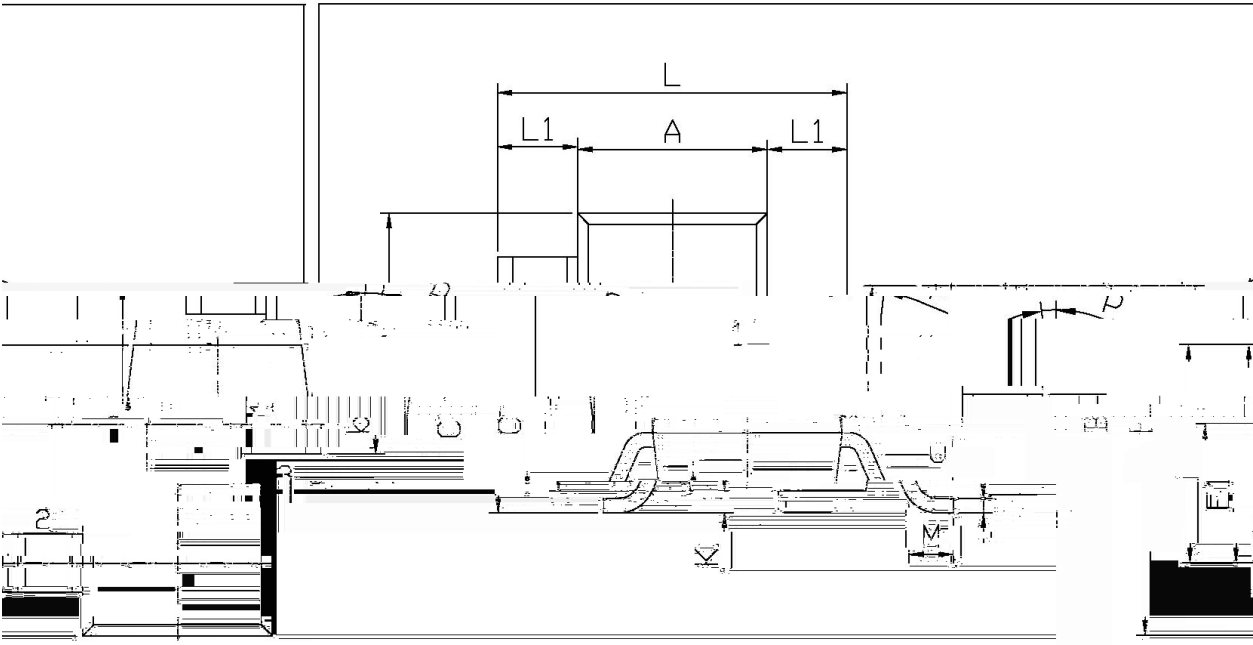




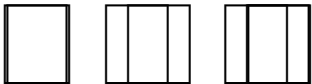
/ Package Dimensions

Symbol; Unit

Symbol; Unit

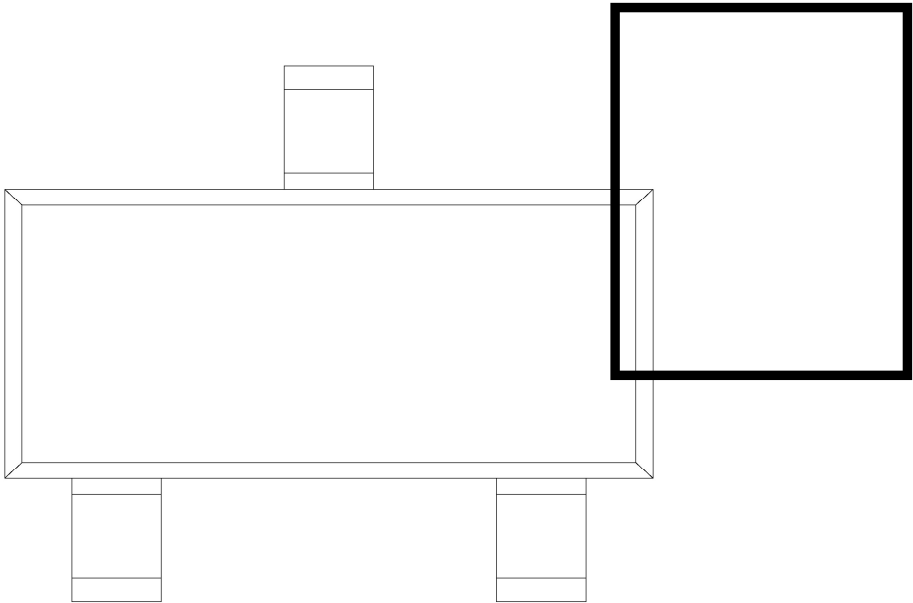


Symbol	Dimensions In Millimeters		Symbol	Dimensions In Millimeters	
	Min	Max		Min	Max
L	2.2	2.7	C	1.30Max	
A	1.15	1.50	B	2.70	3.10
D	0.85	1.05	E	0.35	0.55



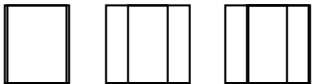
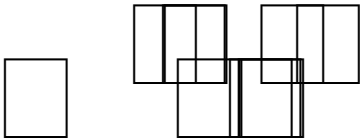


/ Marking Instructions



y z i

i { | } ~ '
i { w m ~ '





() / Temperature Profile for IR Reflow Soldering(Pb-Free)

说明：
、预热温度 ~ °C，时间 ~
、峰值温度 ± °C，时间持续为 ±
、焊接制程冷却速度为 ~ °C

/ Resistance to Soldering Heat Test Conditions

温度： ± °C 时间： ± °C